



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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6N135, 6N136, ICPL4502, ICPL4503

DESCRIPTION

The 6N135, 6N136, ICPL4502 and ICPL4503 devices each consist of an infrared emitting diode, optically coupled to a high speed photo detector transistor. A separate connection for the photodiode bias and output-transistor collector increase the speed by several orders of magnitude over conventional phototransistor couplers by reducing the base-collector capacitance of the input transistor.

FEATURES

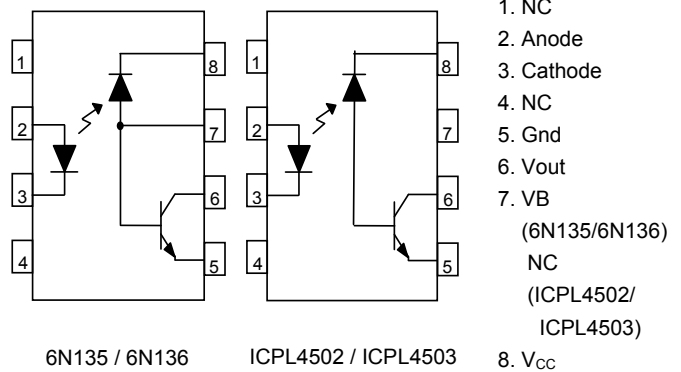
- High speed 1Mbit/s
- High AC Isolation Voltage 5000V_{rms}
- Guaranteed performance from 0°C to 70°C
- Wide Operating temperature range -55°C to 100°C
- Pb Free and RoHS Compliant
- Safety Approvals Pending

APPLICATIONS

- Line Receivers
- Telecommunication Equipments
- Power Transistor Isolation in Motor Drives
- Replacement of Low Speed Phototransistor Optocouplers
- Feedback Loop in Switch Mode Power Supplies
- High Speed Logic Ground Isolation
- Home Appliances

ORDER INFORMATION

- Add G after PN for 10mm lead spacing
- Add SM after PN for Surface Mount,
- Add SMT&R after PN for Surface Mount Tape & Reel



ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Input Diode

Forward Current	25mA
Peak Forward Current (50% duty cycle, 1ms pulse width)	50mA
Peak Transient Current (≤1μs pulse width, 300pps)	1A
Reverse Voltage	5V
Power dissipation	45mW

Output

Output Current	8mA
Peak Output Current	16mA
Emitter-Base Reverse Voltage (6N135 and 6N136 only)	5V
Base Current (6N135 and 6N136 only)	5mA
Output Voltage	-0.5 to 20V
Supply Voltage	-0.5 to 30V
Power Dissipation	100mW

Total Package

Isolation Voltage	5000V _{rms}
Operating Temperature	-55 to 100 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

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6N135, 6N136, ICPL4502, ICPL4503

ELECTRICAL CHARACTERISTICS ($T_A = 0^\circ\text{C}$ to 70°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
Forward Voltage	V_F	$I_F = 16\text{mA}$		1.45	1.8	V
Reverse Voltage	V_R	$I_R = 10\mu\text{A}$	5.0			V
Temperature Coefficient of V_F	$\Delta V_F / \Delta T_A$	$I_F = 16\text{mA}$		-1.9		mV/ $^\circ\text{C}$

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
Logic High Output Current	I_{OH}	$I_F = 0\text{mA}$, $V_O = V_{CC} = 5.5\text{V}$, $T_A = 25^\circ\text{C}$		0.001	0.5	μA
		$I_F = 0\text{mA}$, $V_O = V_{CC} = 15\text{V}$, $T_A = 25^\circ\text{C}$		0.01	1	
		$I_F = 0\text{mA}$, $V_O = V_{CC} = 15\text{V}$			50	
Logic Low Supply Current	I_{CCL}	$I_F = 16\text{mA}$, $V_O = \text{Open}$, $V_{CC} = 15\text{V}$		140	200	μA
Logic High Supply Current	I_{CCH}	$I_F = 0\text{mA}$, $V_O = \text{Open}$, $V_{CC} = 15\text{V}$, $T_A = 25^\circ\text{C}$		0.01	1	μA
		$I_F = 0\text{mA}$, $V_O = \text{Open}$, $V_{CC} = 15\text{V}$			2	

* Typical values at $T_A = 25^\circ\text{C}$



6N135, 6N136, ICPL4502, ICPL4503

ELECTRICAL CHARACTERISTICS ($T_A = 0^\circ\text{C}$ to 70°C unless otherwise specified)

COUPLED

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
Current Transfer Ratio	CTR	6N135 6N136 / ICPL4502 / ICPL4503 $I_F = 16\text{mA}$, $V_O = 0.4\text{V}$ $V_{CC} = 4.5\text{V}$, $T_A = 25^\circ\text{C}$	7 19		50 50	%
		6N135 6N136 / ICPL4502 / ICPL4503 $I_F = 16\text{mA}$, $V_O = 0.5\text{V}$ $V_{CC} = 4.5\text{V}$	5 15			
Logic Low Output Voltage	V_{OL}	6N135 $I_F = 16\text{mA}$, $I_O = 1.1\text{mA}$, $V_{CC} = 4.5\text{V}$, $T_A = 25^\circ\text{C}$		0.18	0.4	V
		6N136 / ICPL4502 / ICPL4503 $I_F = 16\text{mA}$, $I_O = 3\text{mA}$, $V_{CC} = 4.5\text{V}$, $T_A = 25^\circ\text{C}$		0.25	0.4	
		6N135 $I_F = 16\text{mA}$, $I_O = 0.8\text{mA}$, $V_{CC} = 4.5\text{V}$			0.5	
		6N136 / ICPL4502 / ICPL4503 $I_F = 16\text{mA}$, $I_O = 2.4\text{mA}$, $V_{CC} = 4.5\text{V}$			0.5	

* Typical values at $T_A = 25^\circ\text{C}$



6N135, 6N136, ICPL4502, ICPL4503

ELECTRICAL CHARACTERISTICS ($T_A = 0^\circ\text{C}$ to 70°C unless otherwise specified)

Switching Characteristics ($T_A = 0^\circ\text{C}$ to 70°C , $I_F = 16\text{mA}$, $V_{CC} = 5\text{V}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
Propagation Delay Time to Logic Low	T_{PHL}	6N135 $R_L = 4.1\text{k}\Omega$, $T_A = 25^\circ\text{C}$ $R_L = 4.1\text{k}\Omega$		0.35	1.5 2.0	μs
		6N136 / ICPL4502 / ICPL4503 $R_L = 1.9\text{k}\Omega$, $T_A = 25^\circ\text{C}$ $R_L = 1.9\text{k}\Omega$		0.35	0.8 1.0	
Propagation Delay Time to Logic High	T_{PLH}	6N135 $R_L = 4.1\text{k}\Omega$, $T_A = 25^\circ\text{C}$ $R_L = 4.1\text{k}\Omega$		0.5	1.5 2.0	μs
		6N136 / ICPL4502 / ICPL4503 $R_L = 1.9\text{k}\Omega$, $T_A = 25^\circ\text{C}$ $R_L = 1.9\text{k}\Omega$			0.8 1.0	
Common Mode Transient Immunity at Logic High	CM_H	6N135 $I_F = 0\text{mA}$, $V_{CM} = 10\text{Vp-p}$, $R_L = 4.1\text{k}\Omega$, $T_A = 25^\circ\text{C}$	1000			$\text{V}/\mu\text{s}$
		6N136 / ICPL4502 $I_F = 0\text{mA}$, $V_{CM} = 10\text{Vp-p}$, $R_L = 1.9\text{k}\Omega$, $T_A = 25^\circ\text{C}$	1000			
		ICPL4503 $I_F = 0\text{mA}$, $V_{CM} = 1500\text{Vp-p}$, $R_L = 1.9\text{k}\Omega$, $T_A = 25^\circ\text{C}$	15000	20000		
Common Mode Transient Immunity at Logic Low	CM_L	6N135 $I_F = 16\text{mA}$, $V_{CM} = 10\text{Vp-p}$, $R_L = 4.1\text{k}\Omega$, $T_A = 25^\circ\text{C}$	1000			$\text{V}/\mu\text{s}$
		6N136 / ICPL4502 $I_F = 16\text{mA}$, $V_{CM} = 10\text{Vp-p}$, $R_L = 1.9\text{k}\Omega$, $T_A = 25^\circ\text{C}$	1000			
		ICPL4503 $I_F = 16\text{mA}$, $V_{CM} = 1500\text{Vp-p}$, $R_L = 1.9\text{k}\Omega$, $T_A = 25^\circ\text{C}$	15000	20000		

* Typical values at $T_A = 25^\circ\text{C}$



6N135, 6N136, ICPL4502, ICPL4503

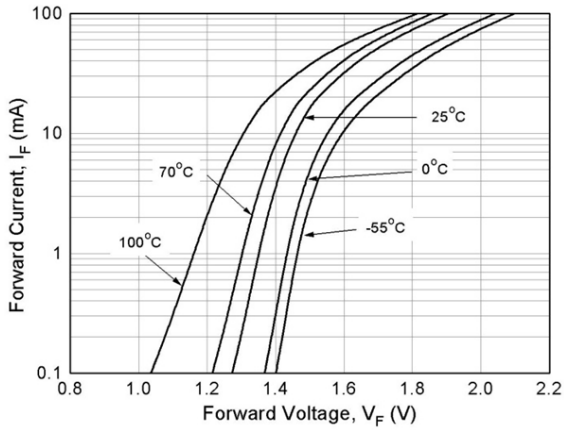


Fig 1 Forward Current vs Forward Voltage

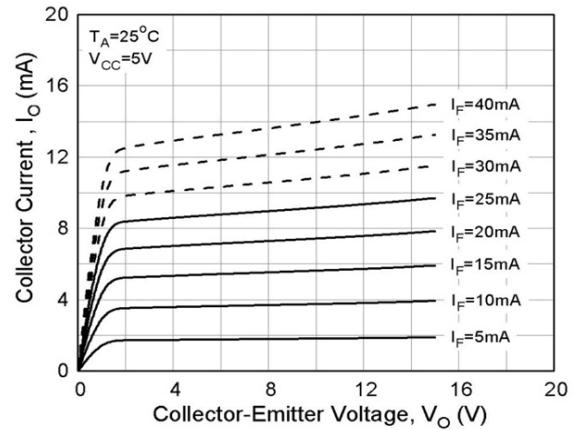


Fig 2 Output Current vs Output Voltage

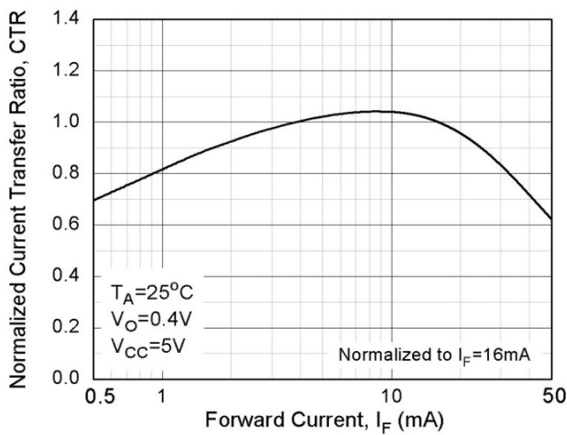


Fig 3 Normalized CTR vs Forward Current

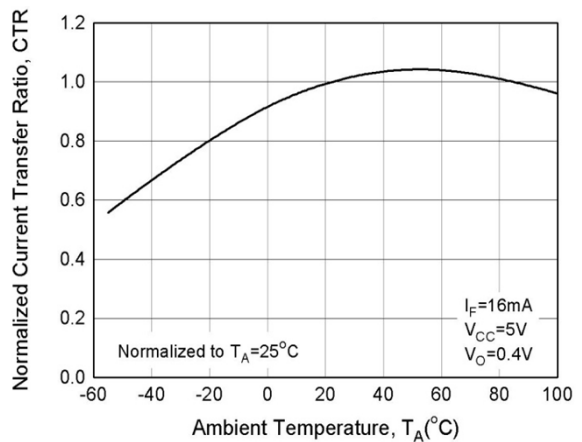


Fig 4 Normalized CTR vs T_A

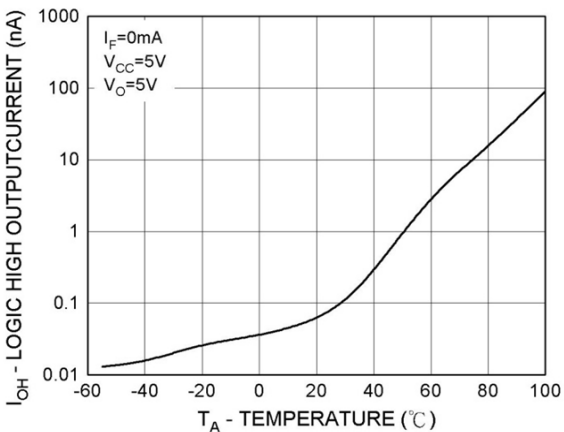


Fig 5 Logic High Output Current vs T_A

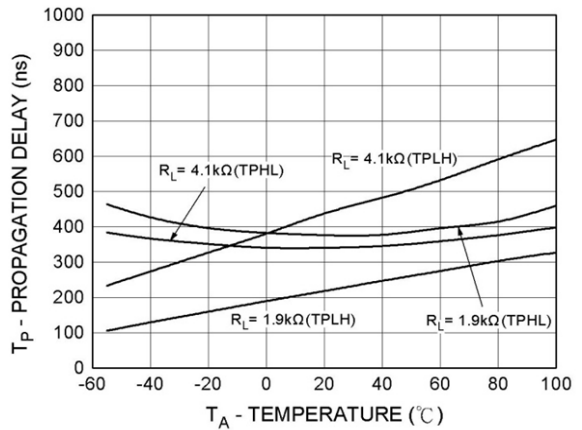


Fig 6 Propagation Delay vs T_A



6N135, 6N136, ICPL4502, ICPL4503

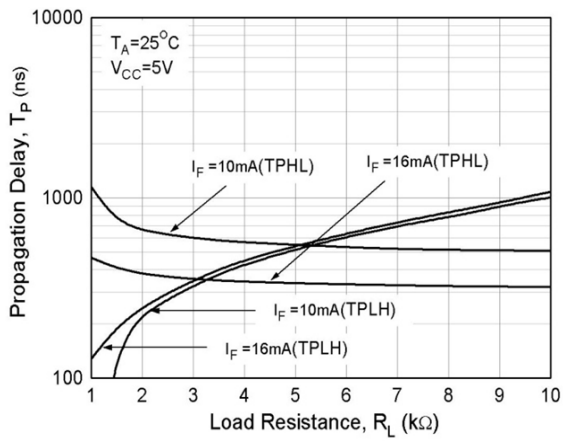
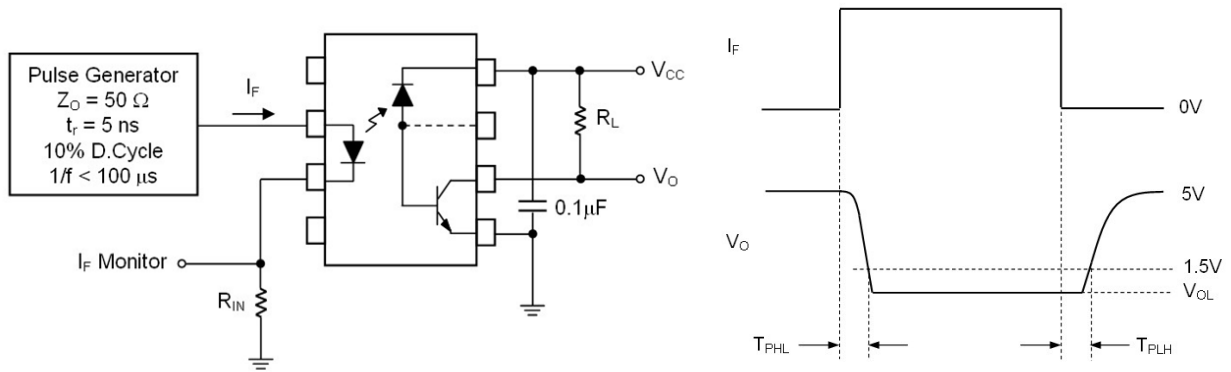


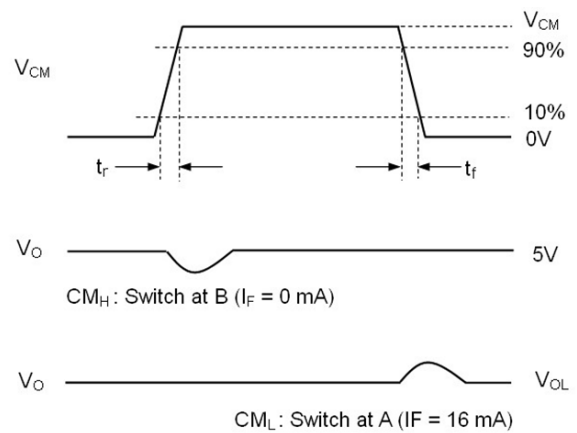
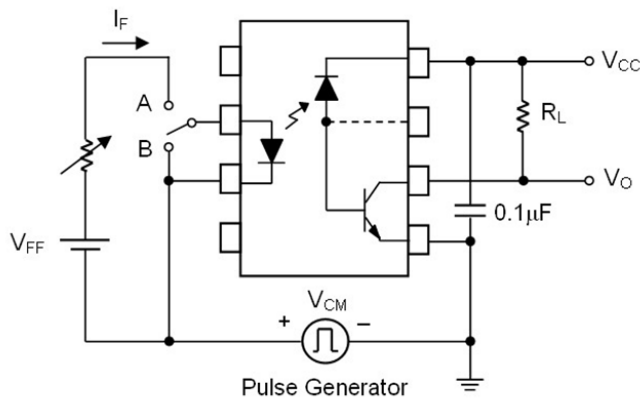
Fig 7 Propagation Delay vs Load Resistance



Switching Time Test Circuit



6N135, 6N136, ICPL4502, ICPL4503



Common Mode Transient Immunity Test Circuit

Note:

Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{CM}/dt on the leading edge of the common mode pulse signal V_{CM} , to assure that the output will remain in a logic high state (i.e., $V_O > 2.0V$).

Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{CM}/dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8V$).



6N135, 6N136, ICPL4502, ICPL4503

ORDER INFORMATION

6N135, 6N136, ICPL4502, ICPL4503			
After PN	PN	Description	Packing quantity
None	6N135, 6N136, ICPL4502, ICPL4503	Standard Dip8	45 pcs per tube
G	6N135G, 6N136G, ICPL4502G, ICPL4503G	10mm Lead Spacing	45 pcs per tube
SM	6N135SM, 6N136SM, ICPL4502SM, ICPL4503SM	Surface Mount	45 pcs per reel
SMT&R	6N135SMT&R, 6N136SMT&R, ICPL4502SMT&R, ICPL4503SMT&R	Surface Mount Tape & Reel	1000 pcs per reel

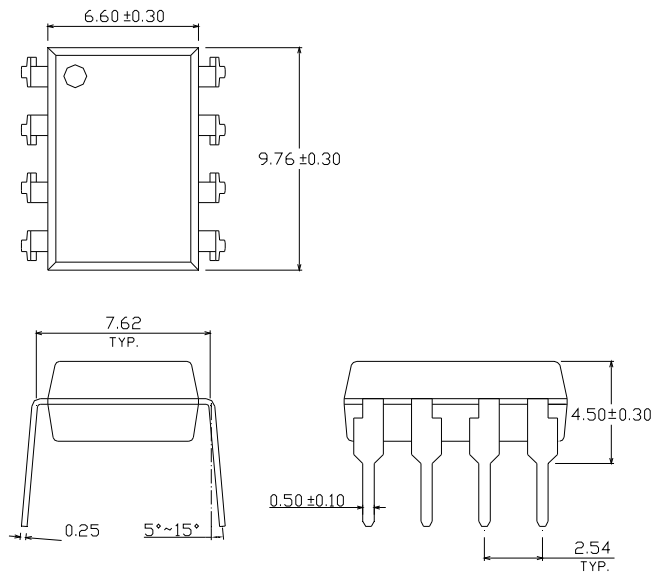


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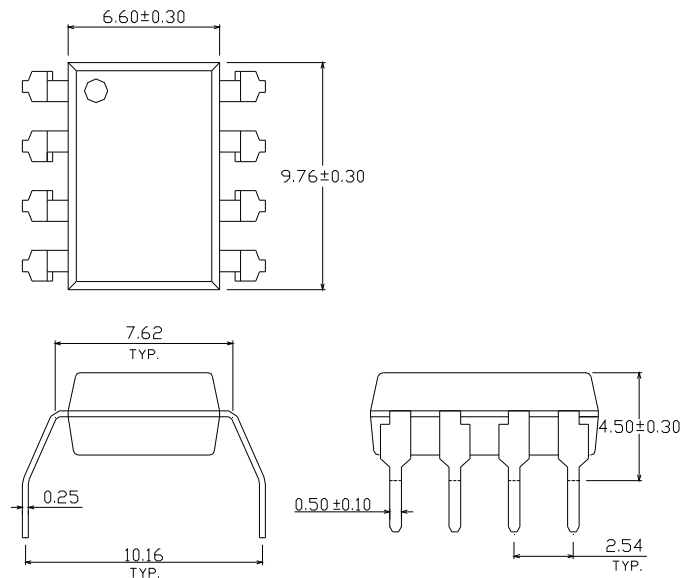
6N135, 6N136, ICPL4502, ICPL4503

PACKAGE DIMENSIONS (mm)

DIP



G FORM

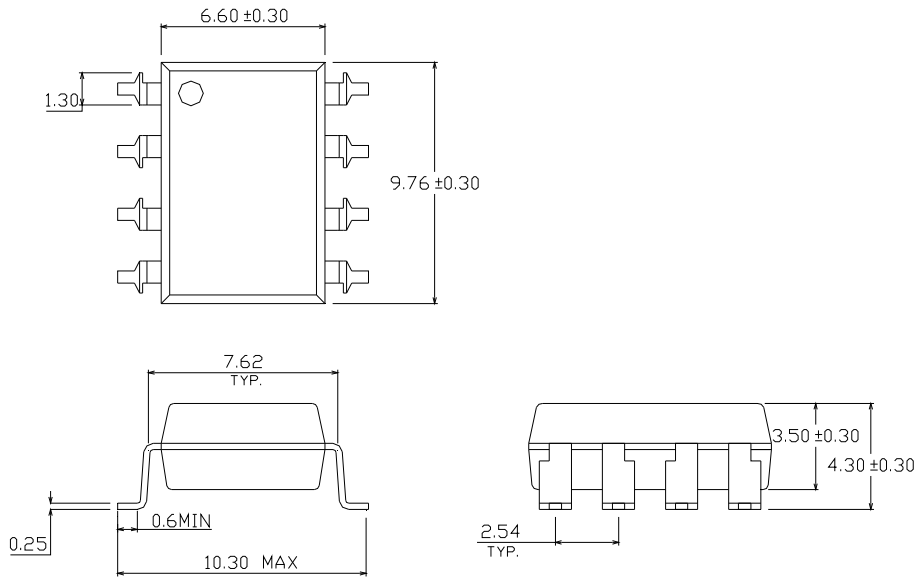




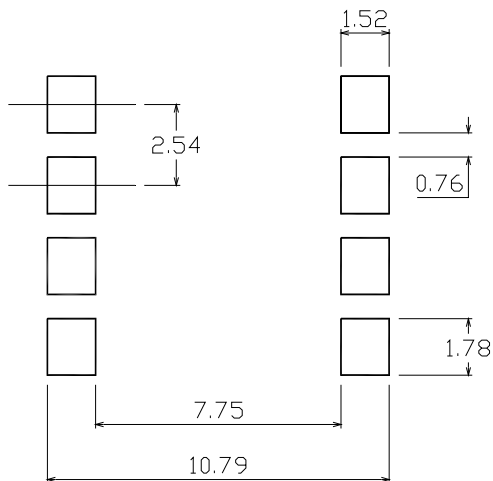
6N135, 6N136, ICPL4502, ICPL4503

PACKAGE DIMENSIONS (mm)

SMD



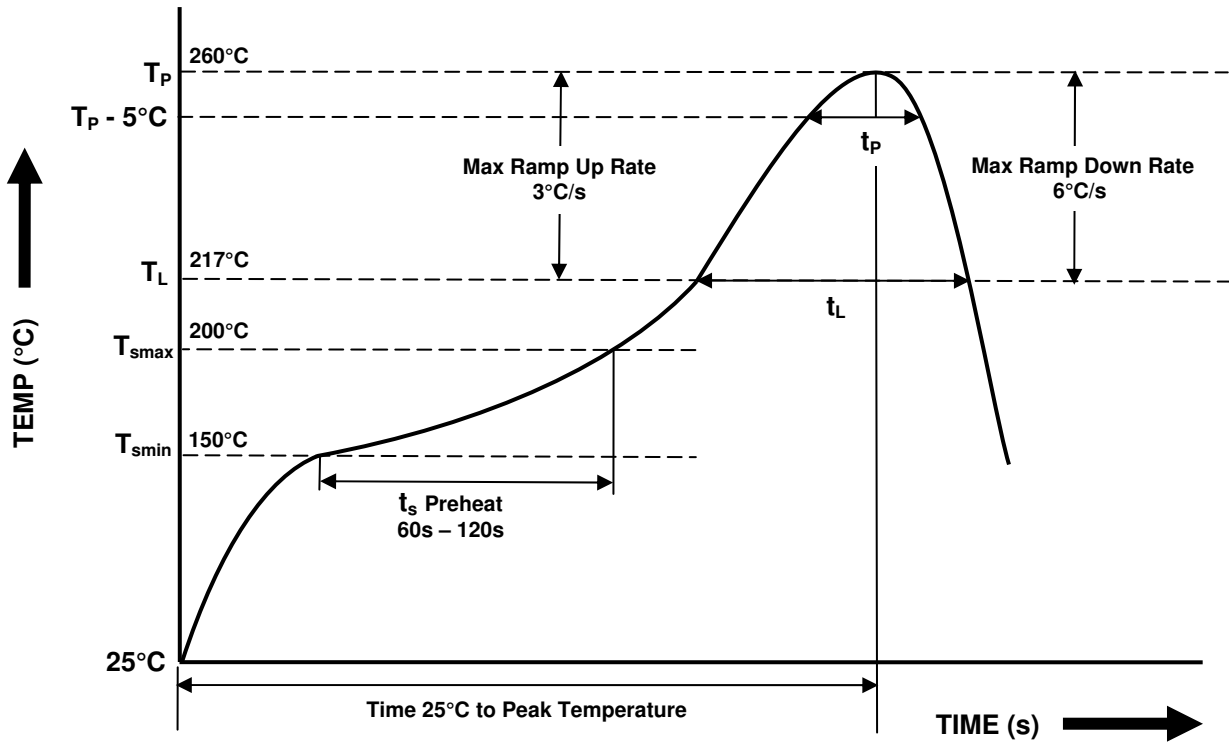
RECOMMENDED PAD LAYOUT FOR SMD (mm)





6N135, 6N136, ICPL4502, ICPL4503

REFLOW SOLDERING TEMPERATURE PROFILE
(One Time Reflow Soldering is Recommended)



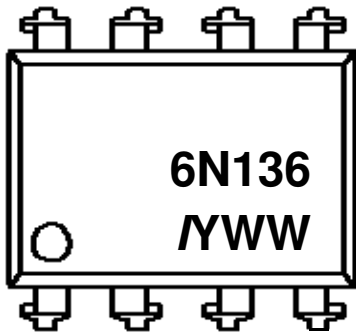
Profile Details	Conditions
Preheat	
- Min Temperature (T_{SMIN})	150°C
- Max Temperature (T_{SMAX})	200°C
- Time T_{SMIN} to T_{SMAX} (t_s)	60s - 120s
Soldering Zone	
- Peak Temperature (T_P)	260°C
- Liquidous Temperature (T_L)	217°C
- Time within 5°C of Actual Peak Temperature ($T_P - 5^\circ\text{C}$)	30s
- Time maintained above T_L (t_L)	60s - 100s
- Ramp Up Rate (T_L to T_P)	3°C/s max
- Ramp Down Rate (T_P to T_L)	6°C/s max
Average Ramp Up Rate (T_{smax} to T_P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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6N135, 6N136, ICPL4502, ICPL4503

DEVICE MARKING (Example 6N136)

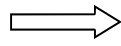
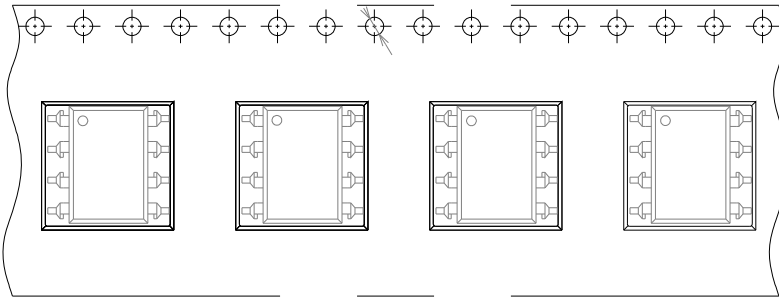


6N136 denotes Device Part Number
Y denotes 1 digit Year code
WW denotes 2 digit Week code
I denotes Isocom

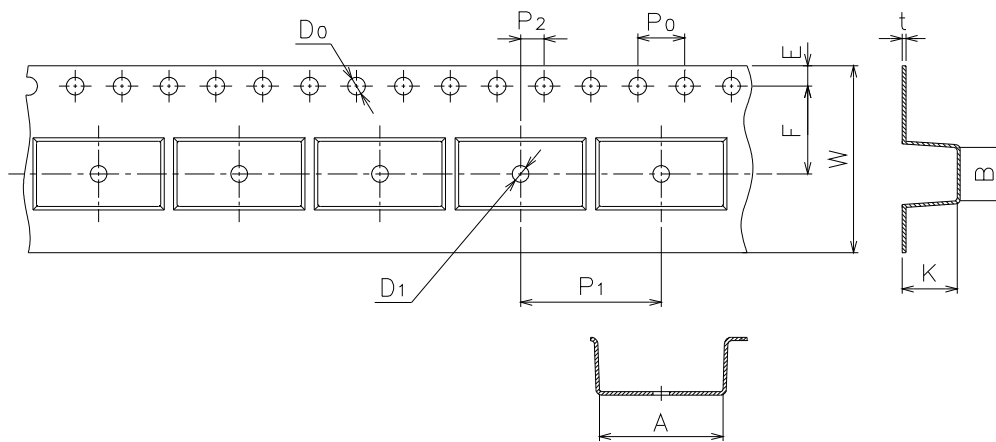


6N135, 6N136, ICPL4502, ICPL4503

TAPE AND REEL PACKAGING



Direction of feed from reel



Dimension No.	A	B	Do	D1	E	F
Dimension(mm)	10.4±0.1	10.0±0.1	1.5±0.1	1.5±0.1	1.75±0.1	7.5±0.1
Dimension No.	Po	P1	P2	t	W	K
Dimension (mm)	4.0±0.1	12.0±0.1	2.0±0.1	0.4±0.1	16.0+0.3/ -0.1	4.5±0.1



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6N135, 6N136, ICPL4502, ICPL4503

NOTES :

- Isocom is continually improving the quality, reliability, function or design and Isocom reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/application where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc., please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales for advice.
- The contents described herein are subject to change without prior notice.
- Do not immerse device body in solder paste.